

NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)  
TRANSMITTAL FORM

Attorney Docket No. TI-31373

Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the  
patent application of:

Inventor(s): Gary P. Morrison  
Darvin R. Edwards  
Leslie Stark

For: **CHIP-SCALE PACKAGES STACKED ON FOLDED INTERCONNECTOR FOR VERTICAL  
ASSEMBLY ON SUBSTRATES**

Enclosed are:

- 5 Sheets of formal drawings and 28 pages of Specification (including Abstract)  
X A Declaration/Power of Attorney  
     Assignment with form PTO 1595

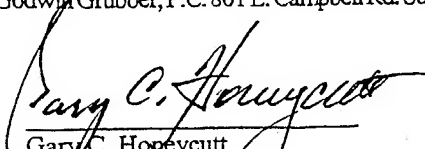
Please amend the specification by inserting before the first line the sentence:  
This application claims priority under 35 U.S.C. § 119 based upon **Provisional Patent  
Application number 60/258,525 filed 12/28/2000.**

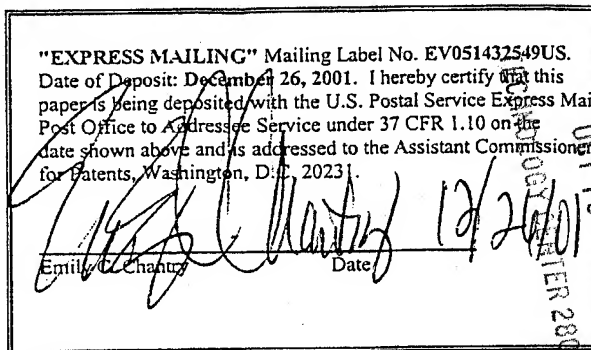
FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	23	-20 =	3	X \$18 =	\$54.00
Independent Claims	6	- 3 =	3	X \$84 =	\$252.00
Total Filing Fee					\$1046.00

Please charge Deposit Account No. 20-0668 in the amount of the Total Fees set forth. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. This form is submitted in triplicate.

All correspondence related to this application may be addressed to the undersigned at Godwin Grubber, P.C. 801 E. Campbell Rd. Suite 655, Richardson, TX 75081.

Date: December 26, 2001

  
Gary C. Honeycutt  
Registration No. 20,250



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